

AMENDMENTS TO THE CLAIMS:

Please amend Claims 1, 10, 18, and 29 as follows:

1. (Currently amended) A method of coating free-standing micromechanical devices, the method comprising:
depositing an organic resin coating material on said micromechanical device in sufficient quantity to substantially encapsulate ~~prevent movement of~~ said micromechanical device, said coating material comprised of at least 35% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes; and curing said coating material.
2. (Original) The method of Claim 1, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
3. (Original) The method of Claim 1, said depositing comprising depositing a coating material having a surfactant.
4. (Original) The method of Claim 1, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
5. (Original) The method of Claim 1, comprising:
rotating said micromechanical device to distribute said organic coating material.
6. (Original) The method of Claim 1, comprising:
rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
7. (Original) The method of Claim 1, said curing comprising:
heating said micromechanical device.
8. (Original) The method of Claim 1, said curing comprising:
heating said micromechanical device at 100° C.
9. (Original) The method of Claim 1, said curing comprising:
heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.

10. (Currently amended) A method of coating free-standing micromechanical devices, the method comprising:
- depositing an organic resin coating material on said micromechanical device in sufficient quantity to substantially encapsulate ~~prevent movement of~~ said micromechanical device, said coating material comprised of at least 35% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes;
- rotating said micromechanical device to distribute said organic coating material;
- and
- curing said coating material.
11. (Original) The method of Claim 10, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
12. (Original) The method of Claim 10, said depositing comprising depositing a coating material having a surfactant.
13. (Original) The method of Claim 10, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
14. (Original) The method of Claim 10, comprising:
- rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
15. (Original) The method of Claim 10, said curing comprising:
- heating said micromechanical device.
16. (Original) The method of Claim 10, said curing comprising:
- heating said micromechanical device at 100° C.
17. (Original) The method of Claim 10, said curing comprising:
- heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.
18. (Currently amended) A method of coating free-standing micromechanical devices, the method comprising:

depositing an organic resin coating material on said micromechanical device in sufficient quantity to substantially encapsulate ~~prevent movement of~~ said micromechanical device, said coating material comprised of at least 40% solids in a solvent, said coating material having a viscosity no greater than 120 centistokes; and curing said coating material.

19. (Original) The method of Claim 18, said depositing comprising depositing a coating material comprised of between 40 and 50% solids.
20. (Original) The method of Claim 18, said depositing comprising depositing a coating material comprised of 49% solids.
21. (Original) The method of Claim 18, said depositing comprising depositing a coating material having a viscosity of 118 centistokes.
22. (Original) The method of Claim 18, said depositing comprising depositing a coating material having a surfactant.
23. (Original) The method of Claim 18, said depositing comprising depositing said coating material in a layer thick enough to cover structures on said micromechanical device after the removal of said solvent.
24. (Original) The method of Claim 18, comprising:
rotating said micromechanical device to distribute said organic coating material.
25. (Original) The method of Claim 18, comprising:
rotating said micromechanical device at 3000 rpm to distribute said organic coating material.
26. (Original) The method of Claim 18, said curing comprising:
heating said micromechanical device.
27. (Original) The method of Claim 18, said curing comprising:
heating said micromechanical device at 100° C.
28. (Original) The method of Claim 18, said curing comprising:
heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.

29. (Currently amended) A method of coating free-standing micromechanical devices, the method comprising:
- depositing a solvent layer on said micromechanical device having moveable structures wider than such structures are high;
 - depositing an organic resin coating material on said solvent layer in sufficient quantity to substantially encapsulate ~~prevent movement of~~ said moveable structures;
 - allowing said organic resin coating material to displace said solvent layer; and
 - curing said organic resin coating material.
30. (Original) The method of Claim 29, said depositing an organic resin coating material comprising depositing an organic resin coating material having a viscosity no greater than 120 centistokes.
31. (Original) The method of Claim 29, said depositing an organic resin coating material comprising depositing an organic resin coating material having a viscosity of 118 centistokes.
32. (Previously presented) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of propylene glycol monomethyl ether.
33. (Previously presented) The method of Claim 29, said depositing an organic resin coating material comprising depositing an organic resin coating material comprised of at least 35% solids in a solvent.
34. (Original) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of solvent and dissolved organic resin.
35. (Previously presented) The method of Claim 29, said depositing a solvent layer comprising depositing a layer of propylene glycol monomethyl ether and dissolved organic resin.
36. (Original) The method of Claim 29, comprising:
- rotating said micromechanical device to distribute said solvent.
37. (Original) The method of Claim 29, comprising:
- rotating said micromechanical device to distribute said organic resin coating material.

38. (Original) The method of Claim 29, comprising:
rotating said micromechanical device to remove excess solvent.
39. (Original) The method of Claim 29, comprising:
rotating said micromechanical device to remove excess organic resin coating material.
40. (Original) The method of Claim 29, said curing comprising:
heating said micromechanical device.
41. (Original) The method of Claim 29, said curing comprising:
heating said micromechanical device at 100° C.
42. (Original) The method of Claim 29, said curing comprising:
heating said micromechanical device to a first elevated temperature to remove a majority of said solvent, and then lowering said temperature to remove additional solvent.